

Technical Characteristics

Electrical	Impedance	50Ω	
	Frequency Range	Straight	0 - 6GHz
VSWR	DWV	Right Angle	0 - 3GHz
	Straight	1000VRMS max.	
Resistance	Right Angle	1.15 max.	
	Contact	1.05:1 max.	
Insulator	Center	≤ 10milliΩ	
	Outer	≤ 5milliΩ	
	Insulator	≥ 5000megaΩ	



SCAN ME

22-02F-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, SOLDERLESS for TCC Group F

22-02F-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, with HeatShrink SOLDERLESS for TCC Group F

22-02K-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, SOLDERLESS for TCC Group K

22-02K-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, with HeatShrink SOLDERLESS for TCC Group K

22-02L2-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, SOLDERLESS for TCC Group L2

22-02L2-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, Right Angle, with HeatShrink SOLDERLESS for TCC Group L2

22-03L2-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, SOLDERLESS for TCC Group L2

22-03L2-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, with HeatShrink SOLDERLESS for TCC Group L2

22-03F-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, SOLDERLESS for TCC Group F

22-03F-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, with HeatShrink SOLDERLESS for TCC Group F

22-03K-E-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, with HeatShrink SOLDERLESS for TCC Group K

22-03K-E-HS-TGN



QMA Male Crimp, Teflon Insulation, Gold Pin, Nickel Plated Body, with HeatShrink SOLDERLESS for TCC Group K